

Docket No.: 202009US-2 DIV

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF

Shigenobu MAEDA : EXAMINER:

SERIAL NO: NEW APPLICATION

FILED: HEREWITH : GROUP ART UNIT:

FOR: MANUFACTURING METHOD OF
SEMICONDUCTOR WAFER,
SEMICONDUCTOR MANUFACTURING
APPARATUS, AND SEMICONDUCTOR
DEVICE

PRELIMINARY AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

Prior to examination on the merits, please amend the above-identified patent
application as follows:

IN THE CLAIMS

Please cancel without prejudice or disclaimer Claims 1-20.

Please add Claims 21-24 as follows:

--21. A method of manufacturing a semiconductor device for building a circuit composed
of combined plural circuit elements into a semiconductor chip, comprising:

expressing a layout pattern of said circuit by using mask patterns respectively prepared
for said plural circuit elements.

22. The method of manufacturing a semiconductor device according to Claim 21,
wherein

each of said mask patterns respectively prepared for said plural circuit elements has a mark for positioning, and

positioning of said mask patterns is performed by superposing one of said marks on another of said marks.

23. A semiconductor device manufactured by the method according to Claim 21.

24. A semiconductor device manufactured by the method according to Claim 22.--

REMARKS

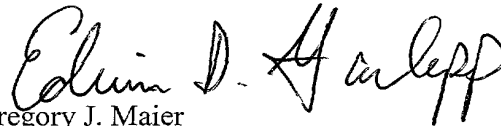
Favorable consideration of this application as presently amended and in light of the following discussion is respectfully requested.

Claims 1-20 canceled, and Claims 21-24 added by way of the present preliminary amendment. Claims 21-24 correspond to non-elected claims 51-54 of the parent application and therefore addition of these claims is not believed to raise a question of new matter.

Accordingly, examination in the merits is believed to be in order and an early and favorable action is respectfully requested.

Respectfully submitted,

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